



Digital Twins and CPS (Cyberphysical Systems)

Guest Editor:

Prof. Dr. Youngchul Bae

Division of Electrical and
Computer Engineering, Chonnam
National University, Daehak-ro
50, Yeosu 59626, Republic of
Korea

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submissions:

closed (30 October 2021)

Message from the Guest Editor

Dear Colleagues,

I would like to cordially invite you to contribute a paper to Special Issue of the open access journal *Applied Sciences*, entitled “Digital twins and CPS (Cyberphysical Systems)”, which aims to present recent developments of digital twins and CPS in the fields of smart systems including academic, research and industries, and so on.

This Special Issue contains digital twins, CPS, and their related themes or applications. I invite you to submit your research on these topics, in the form of original research papers and articles.

Prof. Dr. Youngchul Bae





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Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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